

MATERIAL DECLARATION SHEET



Material Number	CM453232 series (151-102)			
Product Line	Wound Chip Inductor			
Compliance Date	2022/9/1			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	Ferrite	0.03	Iron oxide (Fe2O3)	1309-37-1	66.0	18	27.27
				Nickel oxide (NiO)	1313-99-1	8.0	2.18	
				Zinc oxide (ZnO)	1314-13-2	22.0	6	
				Copper oxide(CuO)	1317-38-0	4.0	1.09	
2	Winding Wire	Copper	0.015	Copper(Cu)	7440-50-8	95.0	12.95	13.63
				Polyesterimide	confidential	5.0	0.68	
3	Terminal	Copper	0.035	Copper (Cu)	7440-50-8	95.0	30.23	31.82
				Tin (Sn)	7440-31-5	5.0	1.59	
4	Adhesive	Resin	0.013	Bisphenol A diglycidyl ether	25068-38-6	65.0	7.68	11.82
				Dicyandiamide	461-58-5	6.0	0.72	
				Titanium Dioxide	13463-67-7	4.0	0.47	
				Silicon dioxide	14808-60-7	25.0	2.95	

MATERIAL DECLARATION SHEET



6	Molding Compound	Silica	0.005	silica	60676-86-0	69.0	3.14	4.55
				Antimony(III) oxide	1309-64-4	2.5	0.11	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0	0.68	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	0.46	
				Brominated epoxy resin	40039-93-8	2.5	0.11	
				Carbon black	1333-86-4	1.0	0.05	
7	Varnish	Resin	0.009	Synthetic resin	63148-69-6	100.0	8.18	8.18
8	Solder	Tin	0.003	Tin (Sn)	7440-31-5	100.0	2.73	2.73
Total weight			0.11					

This Document was updated on: 2022/9/1

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.